

74F38-Q100

Quad 2-input NAND buffer (open collector)

Rev. 1 — 19 May 2014

Product data sheet

1. General description

The 74F38-Q100 provides four 2-input NAND functions with open-collector outputs.

2. Features and benefits

- Commercial range (0 °C to +70 °C)

3. Ordering information

Table 1. Ordering information

Type number	Package			
	Temperature range	Name	Description	Version
N74F38D-Q100	0 °C to +70 °C	SO14	plastic small outline package; 14 leads; body width 3.9 mm	SOT108-1



4. Functional diagram

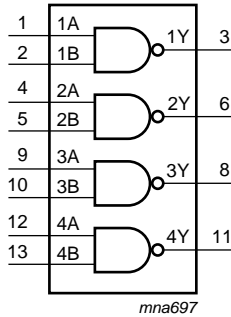


Fig 1. Logic symbol

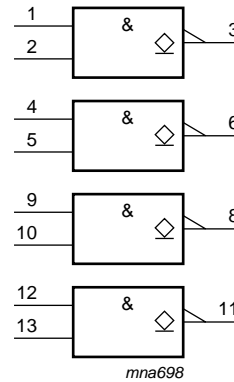


Fig 2. IEC logic symbol

5. Pinning information

5.1 Pinning

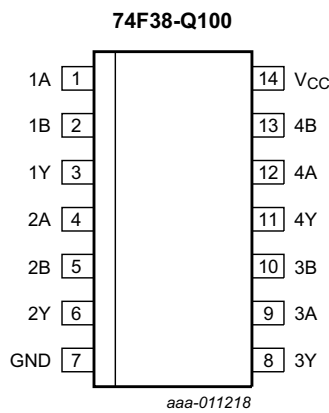


Fig 3. Pin configuration DIP14 and SO14 package

5.2 Pin description

Table 2. Pin description

Symbol	Pin	Description	Unit load HIGH/LOW	Load value ^{[1][2]} HIGH/LOW
1A, 2A, 3A, 4A	1, 4, 9, 12	data input	1.0/2.0	20 μ A/1.2 mA
1B, 2B, 3B, 4B	2, 5, 10, 13	data input	1.0/2.0	20 μ A/1.2 mA
1Y, 2Y, 3Y, 4Y	3, 6, 8, 11	data output	OC/106.7	OC/64 mA
GND	7	ground (0 V)	-	-
V _{CC}	14	supply voltage	-	-

[1] One FAST Unit Load (UL) is defined as 20 μ A in HIGH state, 0.6 mA in LOW state.

[2] OC = open collector.

6. Functional description

Table 3. Function table^[1]

Input		Output
nA	nB	nY
L	L	H
L	H	H
H	L	H
H	H	L

[1] H = HIGH voltage level; L = LOW voltage level; X = don't care; Z = high-impedance OFF-state.

7. Limiting values

Table 4. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Min	Max	Unit
V _{CC}	supply voltage		-0.5	+7.0	V
V _I	input voltage		^[1] -0.5	+7.0	V
V _O	output voltage	output in HIGH-state	^[1] -0.5	V _{CC}	V
I _{IK}	input clamping current	V _I < 0 V	-30	+5	mA
I _O	output current	output in LOW-state	-	128	mA
T _{amb}	ambient temperature	in free-air	^[2] 0	70	°C
T _{stg}	storage temperature		-65	+150	°C

[1] The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

[2] The performance capability of a high-performance integrated circuit in conjunction with its thermal environment can create junction temperatures which are detrimental to reliability. The maximum junction temperature of this integrated circuit should not exceed 150 °C.

8. Recommended operating conditions

Table 5. Recommended operating conditions

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
V_{CC}	supply voltage		4.5	5.0	5.5	V
V_{IH}	HIGH-level input voltage		2.0	-	-	V
V_{IL}	LOW-level input voltage		-	-	0.8	V
V_{OH}	HIGH-level output voltage		-	-	4.5	V
I_{IK}	input clamping current		-18	-	-	mA
I_{OL}	LOW-level output current		-	-	64	mA

9. Static characteristics

Table 6. Static characteristics

Symbol	Parameter	Conditions	25 °C			0 °C to +70 °C		Unit
			Min	Typ ^[1]	Max	Min	Max	
V_{IK}	input clamping voltage	$V_{CC} = 4.5 \text{ V}$; $I_{IK} = -18 \text{ mA}$	-1.2	-0.73	-	-1.2	-	V
V_{OL}	LOW-level output voltage	$V_{CC} = 4.5 \text{ V}$; $V_{IL} = 0.8 \text{ V}$; $V_{IH} = 2.0 \text{ V}$						
		$I_{OL} = 64 \text{ mA}$						
		$V_{CC} = \pm 10 \%$	-	-	-	-	0.55	V
		$V_{CC} = \pm 5 \%$	-	0.42	-	-	0.55	V
I_I	input leakage current	$V_{CC} = 0 \text{ V}$; $V_I = 7.0 \text{ V}$	-	-	-	-	100	μA
I_{IH}	HIGH-level input current	$V_{CC} = 5.5 \text{ V}$; $V_I = 2.7 \text{ V}$	-	-	-	-	20	μA
I_{IL}	LOW-level input current	$V_{CC} = 5.5 \text{ V}$; $V_I = 0.5 \text{ V}$	-	-	-	-20	-	μA
I_{CC}	supply current	$V_{CC} = 5.5 \text{ V}$						
		$V_I = \text{GND}$	-	4	-	-	7	mA
		$V_I = 4.5 \text{ V}$	-	22	-	-	30	mA

[1] All typical values are measured at $V_{CC} = 5 \text{ V}$.

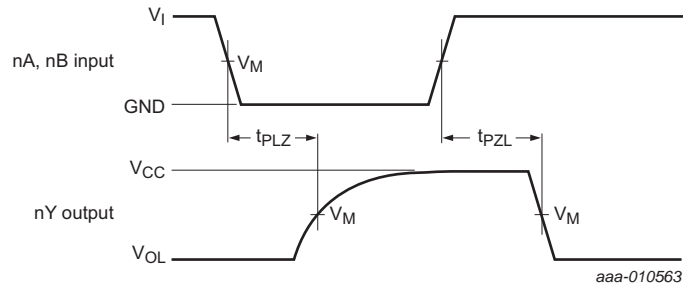
10. Dynamic characteristics

Table 7. Dynamic characteristics

$GND = 0 \text{ V}$. Test circuit is shown in [Figure 6](#).

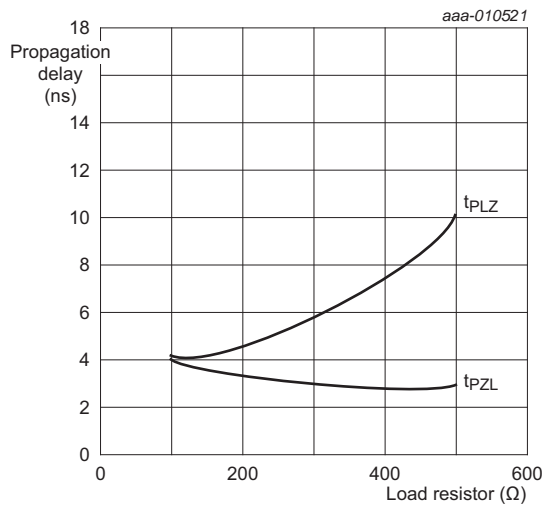
Symbol	Parameter	Conditions	25 °C; $V_{CC} = 5.0 \text{ V}$			0 °C to +70 °C; $V_{CC} = 5.0 \text{ V} \pm 0.5 \text{ V}$		Unit
			Min	Typ	Max	Min	Max	
t_{PZL}	OFF-state to LOW propagation delay	nA, nB to nY; see Figure 4	1.5	3.0	5.0	1.5	5.5	ns
t_{PLZ}	LOW to OFF-state propagation delay	nA, nB to nY; see Figure 4	7.5	10.0	12.5	7.5	13.0	ns

11. Waveforms



$V_M = 1.5\text{ V}$
 V_{OL} is a typical output voltage level that occurs with the output load.

Fig 4. Propagation delay for inverting outputs



When using open collector parts, the value of the pull-up resistor greatly affects the value of the t_{PLZ} . For example, changing the specified pull-up resistor value from $500\ \Omega$ to $100\ \Omega$ improves the t_{PLZ} up to 50% with only a slight increase in the t_{PZL} . However, if the value of the pull-up resistor is changed, the user must ensure that the total I_{OL} current through the resistor and the total I_{IL} of the receivers, does not exceed the I_{OL} minimum specification.

Fig 5. Typical propagation delays versus load for open collector outputs

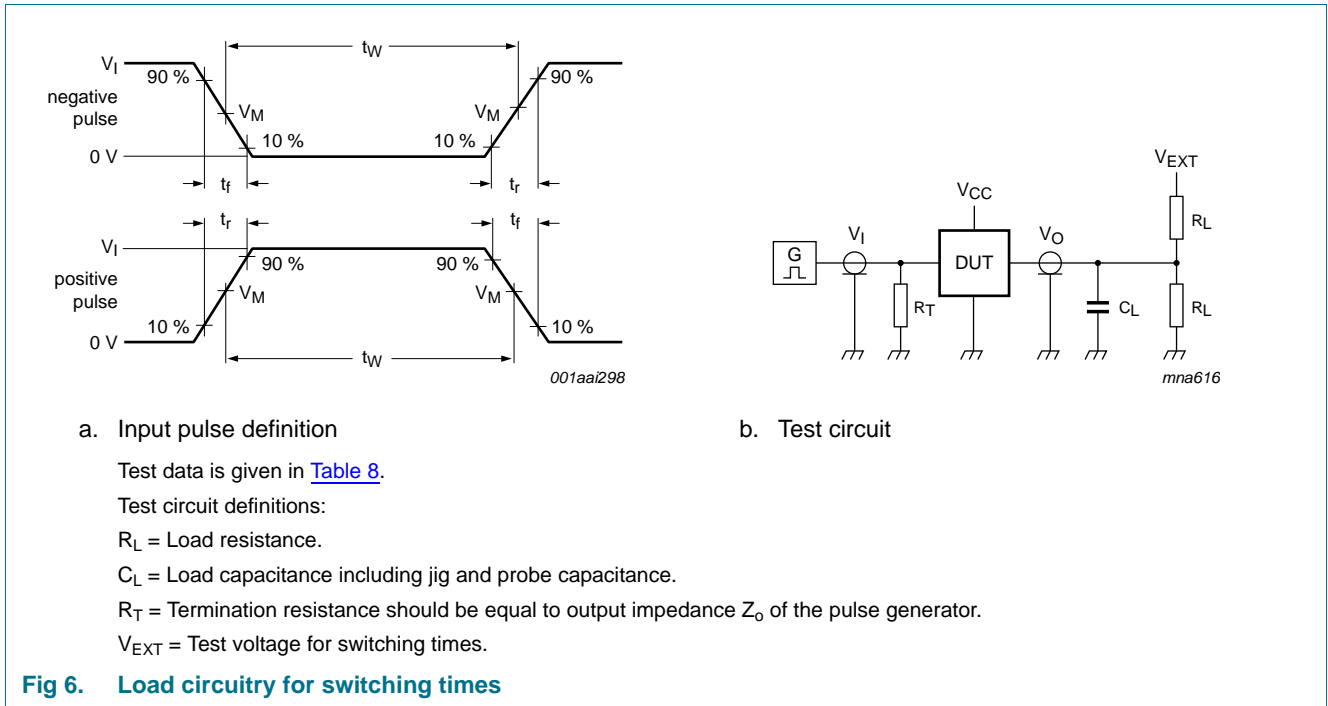


Table 8. Test data

Input				Load		V_{EXT}
V_I	f_i	t_w	t_r, t_f	C_L	R_L	t_{PZL}, t_{PLZ}
3.0 V	1 MHz	500 ns	≤ 2.5 ns	50 pF	500 Ω	7.0 V

12. Package outline

SO14: plastic small outline package; 14 leads; body width 3.9 mm

SOT108-1

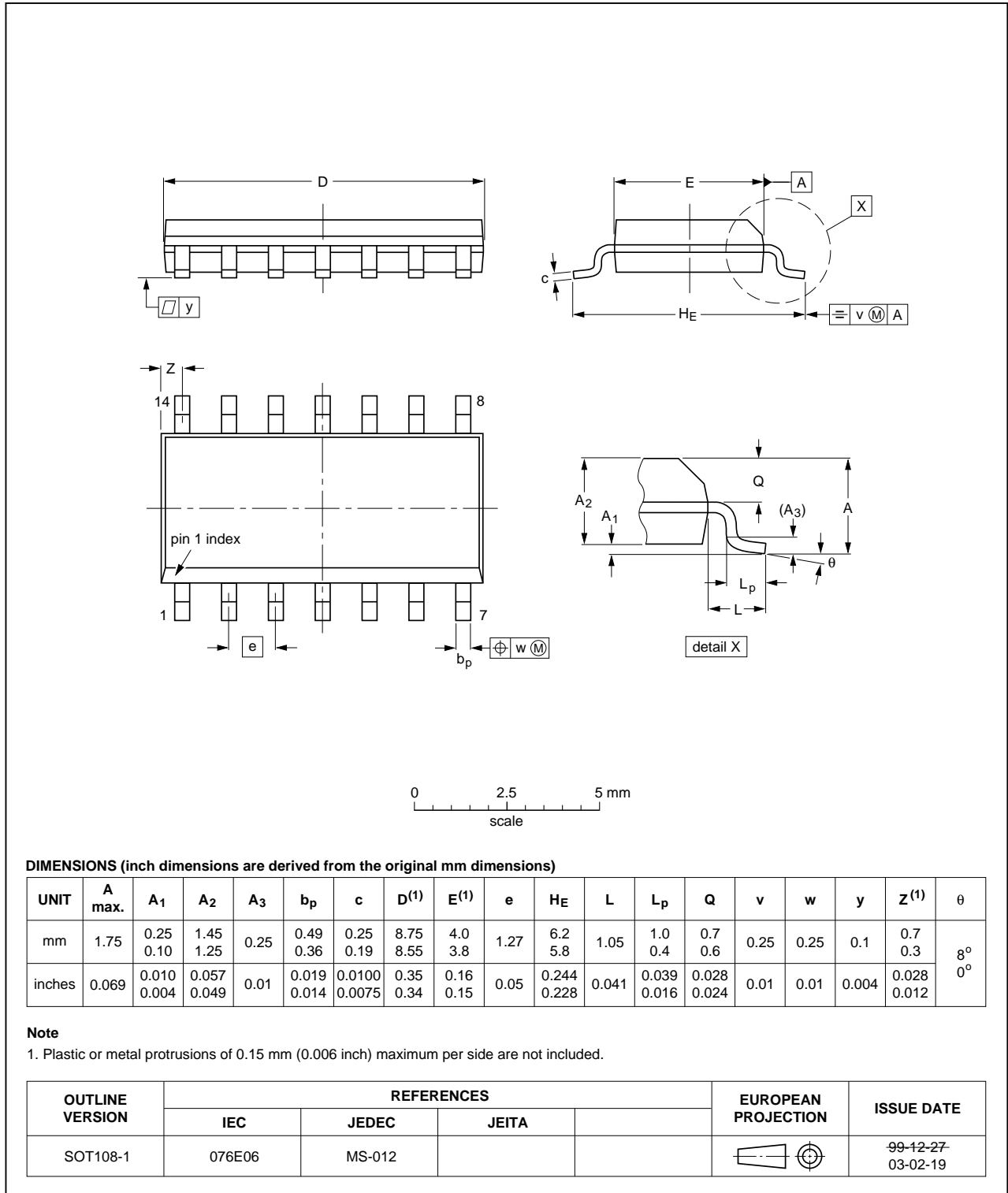


Fig 7. Package outline SOT108-1 (SO14)

13. Revision history

Table 9. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
74F38_Q100 v.1	20140519	Product data sheet	-	-

14. Legal information

14.1 Data sheet status

Document status ^{[1][2]}	Product status ^[3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
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Product [short] data sheet	Production	This document contains the product specification.

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[2] The term 'short data sheet' is explained in section "Definitions".

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Date of release: 19 May 2014

Document identifier: 74F38-Q100

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